APPARATUS AND METHOD FOR DIRECT SILICON CHIP ATTACHMENT TO A LEAD FRAME

ABSTRACT OF THE DISCLOSURE

An integrated circuit package (30) and method for producing the same is disclosed that comprises a printed circuit board (70) having an opening (86) and first and second surfaces (92, 94), and a silicon chip (50) attached to the printed circuit board (70) by a metal layer (62) and an adhesive layer (60) that provide a strong attachment between silicon chip (50) and printed circuit board (70). The metal layer (62) may be disposed on the printed circuit board (70) with the adhesive layer (60) disposed between the metal layer (62) and the chip (50) or the metal layer (62) may be disposed on the chip (50) with the adhesive layer (60) disposed between the metal layer (62) and the printed circuit board (70).

Figure 1